



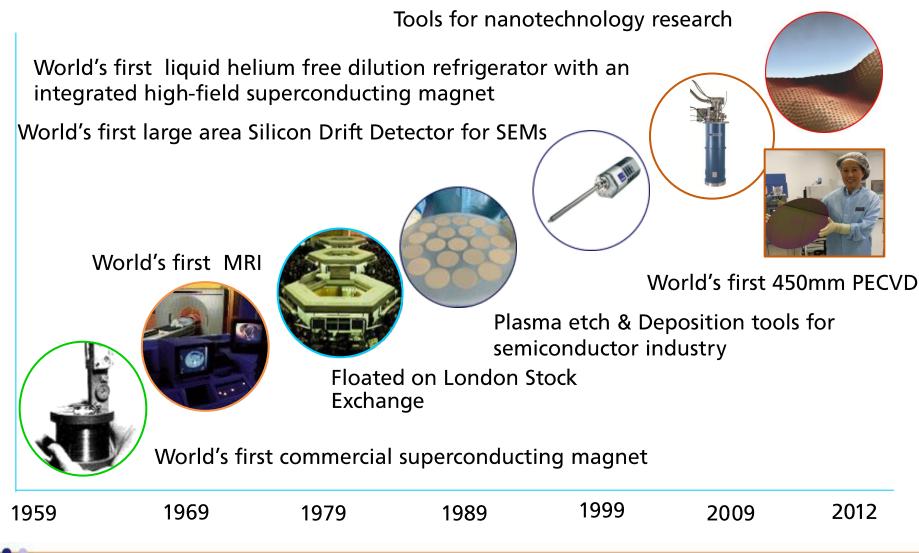
## Oxford Instruments Nanotechnology Tools

Capital Equipment considerations for 2d materials moving from Lab to Fab

> Dr Ravi Sundaram HVM Graphene+ 2014 Conference Oxford, UK 15 May www.hvm-uk.com

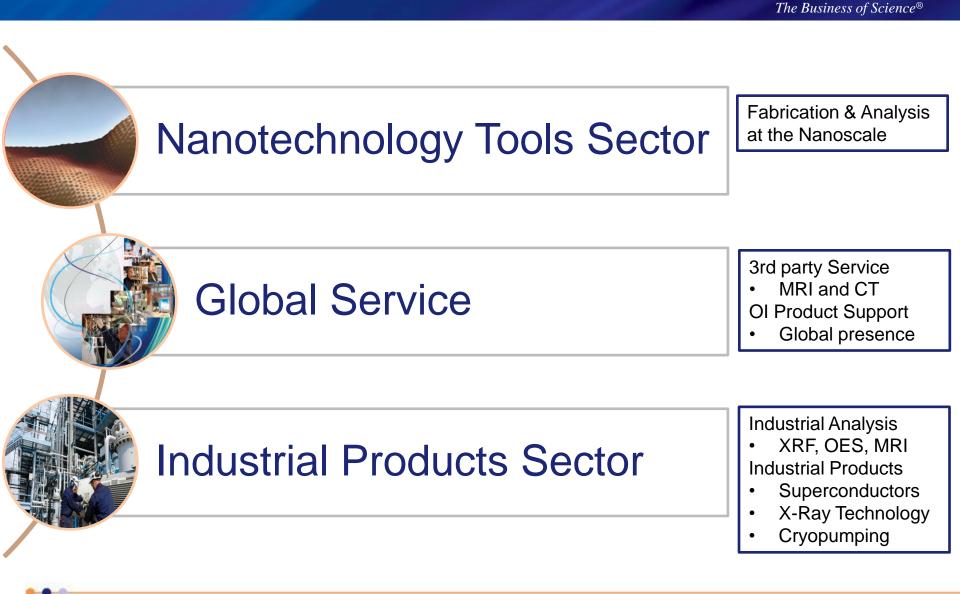
## **Our History**





## **Our Businesses**





## **OI Nanotechnology Tools Sector**





#### Partnering with customers and suppliers to:

- Understand needs of the research field and develop tools to meet requirement
- Provide world leading tools and process solutions to emerging production markets





#### **Challenges**



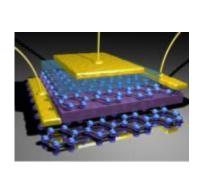
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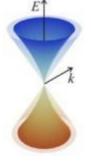
#### **Electronic devices**

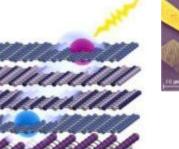
- Reducing growth costs
- Wafer level scaling
- Handling thin films •
- Band gap engineering
- Encapsulation
- Atomic level lithography
- New device Physics
- System integration

#### Energy Storage

- **Electrochemical interactions**
- Development of heterostructures
- Producing stable doping
- **Composite Materials** 
  - Producing materials cost effectively
  - Bonding with polymer matrix
- Sensors
  - Selectivity
  - Surface activation and functionalisation

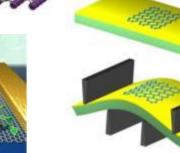






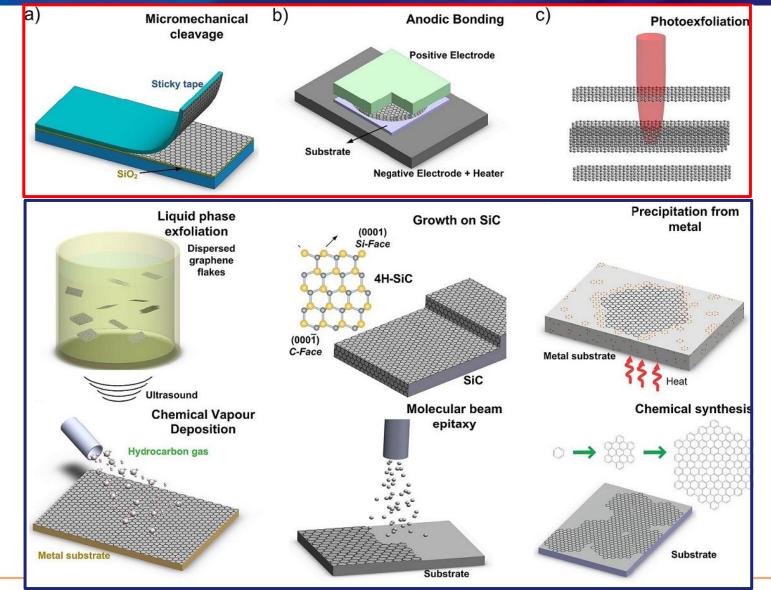






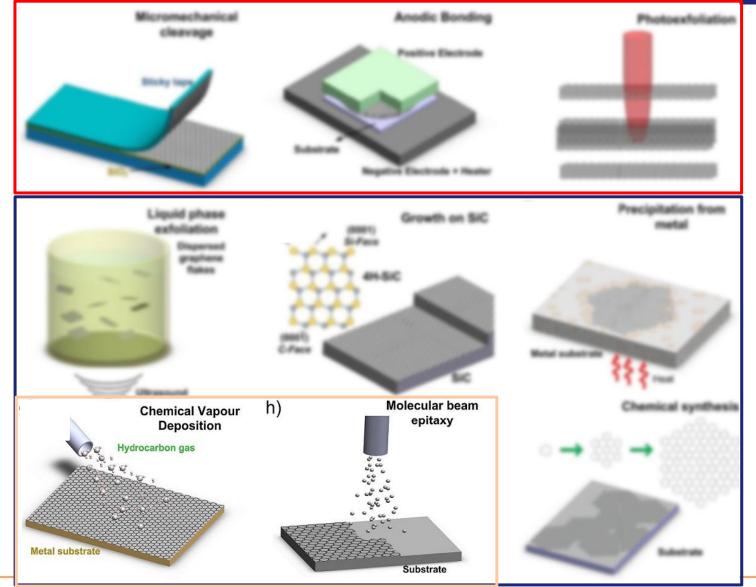
#### 2d materials synthesis

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# Solutions for fundamental research

MBE and Cluster tools



#### MBE - Wafer scale fabrication of Graphene based devices

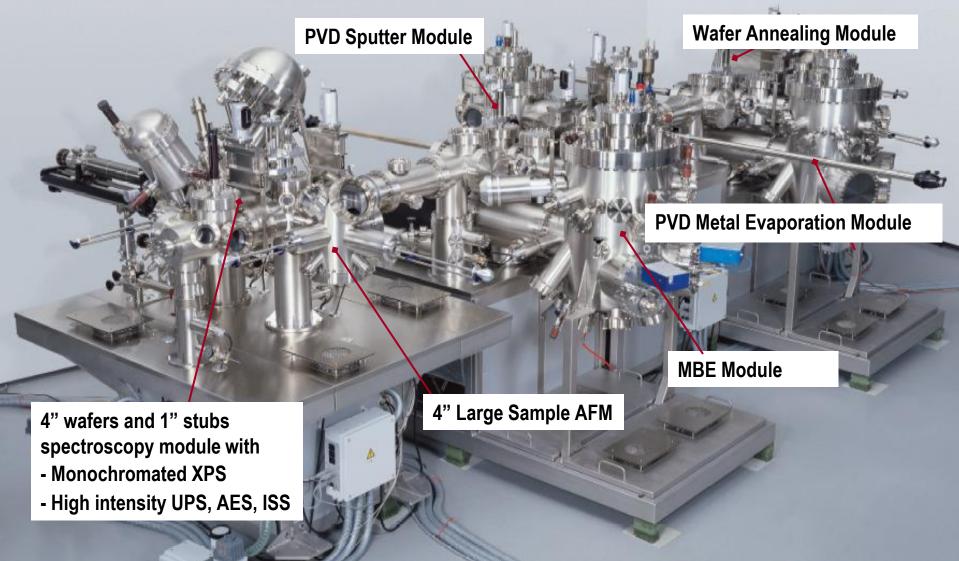


- Use of wafer-scaled Graphene in spintronics
- Magnetic devices based on spin transfer torque in graphene
- Most advanced UHV and source technology tailored to the application

### Combination of Growth and Analysis Systems



INSTRUMENTS





# Applied Research and Pilot line tools

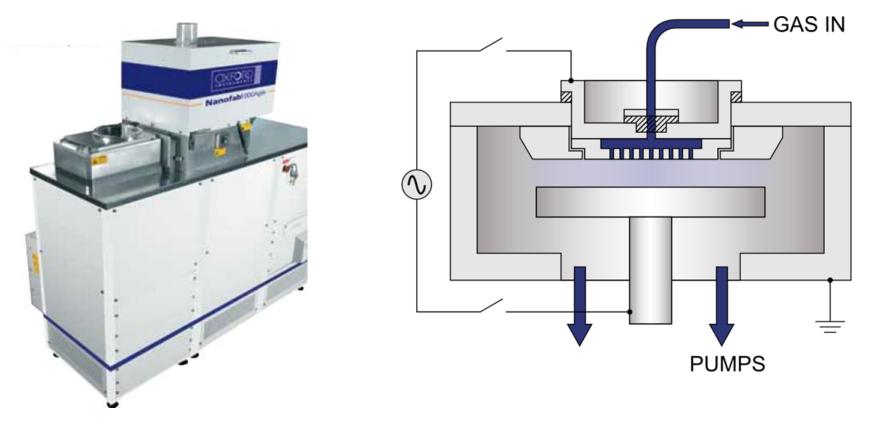
## CVD, PECVD and ALD

#### Nanofab 100



#### PECVD

• 200 mm substrate, parallel plate configuration



#### Nanofab 100: A multi process tool



- PECVD/ CVD process, cold wall
- 400°C for silicon nanowires
- 700°C for multiwall carbon nanotubes, ZnO
- 800°C for single wall nanotubes
- 1000°C graphene
- External delivery module for liquid precursors

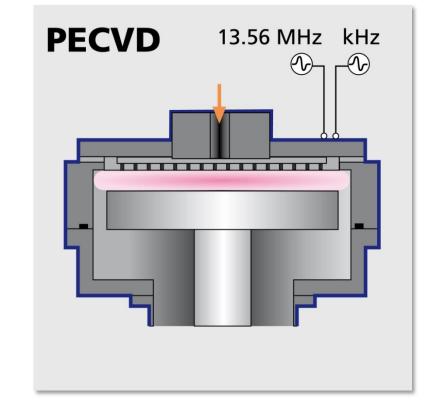




#### **PECVD Hardware**

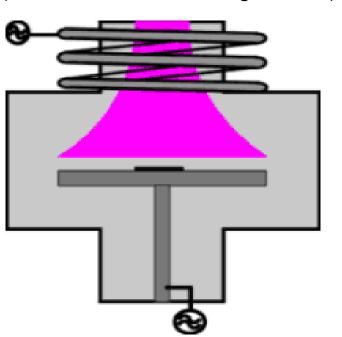


- Dual frequency 13.56MHz and 50KHz power applied to upper electrode enabling stress control and film densification
- Gas inlet and showerhead assembly designed for uniform gas flow and low particle generation
- View port and optical emission spectroscopy (OES) port



- High density films for much lower temperatures than PECVD.
- High density plasmas in low pressure range
- Low damage deposition on to temperature sensitive substrates
- Processes specifically developed to minimise surface ion damage

Inductively Coupled coil (connected to 13.56MHz generator)

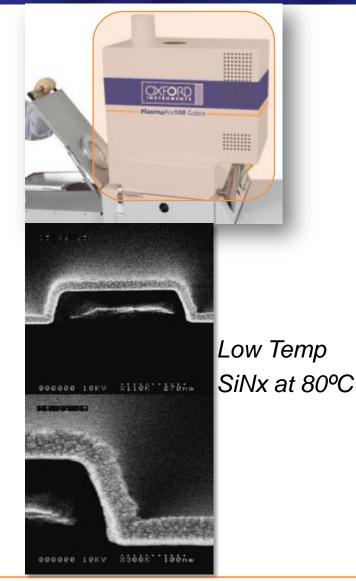




#### **Cobra - High Density Plasma Source**



- Active spacer for independent uniformity control and increased plasma density
- Optimised AMU which delivers greater efficiency, enhanced process repeatability and hardware reliability
- Easy striking (via matching unit control and/or electromagnet option)
- Low power operation (<200W) for low damage/nano applications
- Diagnostic ports available for OES, interferometry, and in-line RF diagnostics



## **Process Capability**



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Tool Process	Nanofab 700	Nanofab 800 Agile	Nanofab 1000 Agile
Thin Film Process	SiO <sub>x</sub> , SiN <sub>x</sub> ,aSiC, aSi, <i>µc</i> -Si, <i>poly</i> Si*	SiO <sub>x</sub> , SiN <sub>x</sub> , <i>a</i> SiC, aSi, <i>µc</i> -Si <i>poly</i> Si	SiO <sub>x</sub> , SiN <sub>x</sub> , <i>a</i> SiC, <i>a</i> Si, <i>µc</i> -Si, <i>poly</i> Si
1D Nano materials	MWNTs Si, Ge NWs ZnO NWs	MWNTs, SWNTs* Si, Ge NWs	MWNTs, SWNTs Si, Ge NWs
2D Nano materials		NCG, Vertical Graphene	NCG, Vertical, CVD Graphene, BN,* MoS <sub>2</sub> *
O <sub>2</sub> compatibility (>400°C)	Compatible	Non- Compatible	Non- Compatible

\* Please contact OIPT for more detail on the marked material with the tool.

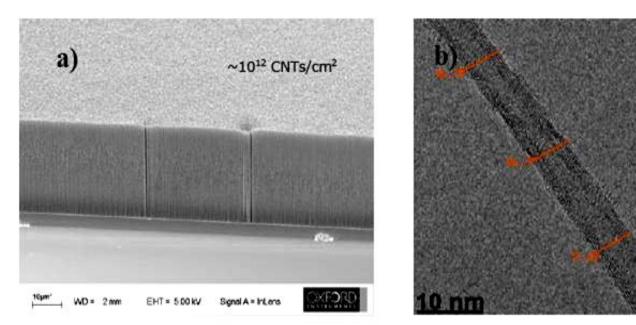
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## **Carbon Nanotubes**





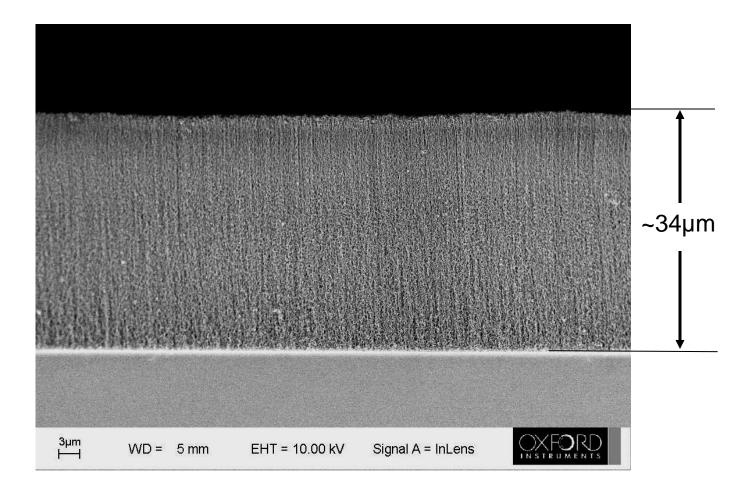


Results courtesy IMEC

• MWCNT growth on Fe/Ni

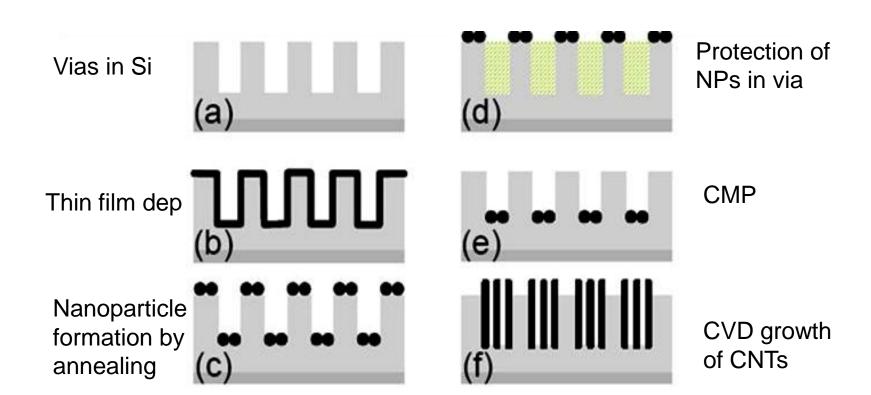
### **Dense Bush Carbon Nanotubes**





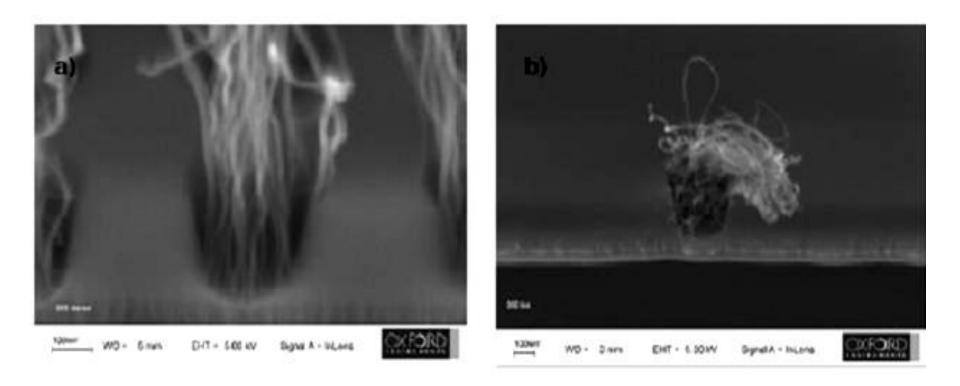






#### Via interconnect CNT growth







## ALD

Dielectric deposition for nanoelectronics



#### FlexAL-Atomic Layer Deposition Systems: Dielectrics deposition for 2d nanoelectronics

- Load lock System
- Extensive process capability
  - Precursor options for research (up to 100g) and production (up to 500g)
  - Up to 8 liquid/solid precursors (3+3+1+1)
  - Up to 10 gas precursors
  - Water as standard
  - Ozone as option
- Clusterable
- Optional turbo pump for moisture sensitive nitrides



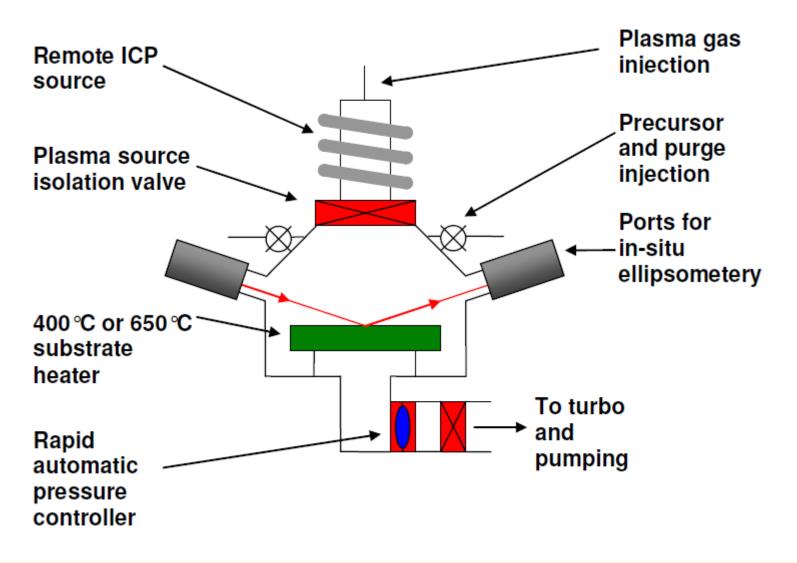




#### **FlexAl in situ Analysis**



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## **Graphene and other 2d Materials**

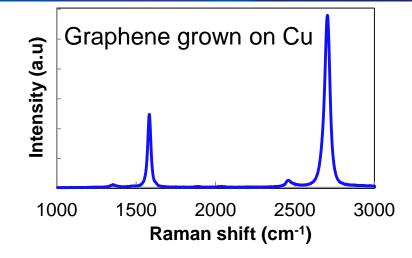
Nanofab tools



#### **Graphene Growth**



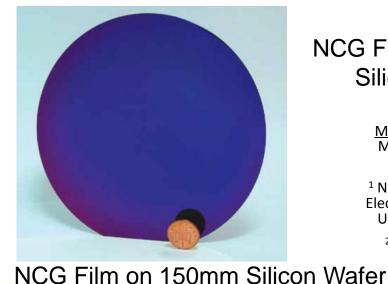




### Nanofab<sup>™</sup> 1000Agile

- High performance growth of nanotubes & nanowires
- PECVD and ICP options
- Rigorous process control





#### NCG Film on 150mm Silicon Wafer

<u>Marek E. Schmidt</u><sup>1)</sup>, Cigang Xu<sup>2)</sup>, Mike Cooke<sup>2)</sup>, Hiroshi Mizuta<sup>1)</sup>, and Harold M. H. Chong<sup>1)</sup>

<sup>1</sup> Nano Research Group, School of Electronics and Computer Science, University of Southampton, UK

<sup>2</sup> Oxford Instruments Plasma Technology, Bristol, UK

# Precursor Delivery: Towards other 2D materials

- OIPT already has proven capability for the growth of novel materials using liquid precursors
  - PECVD
  - ALD
- Combining these techniques could advance the fabrication of hetero-structures and commercial viable devices based upon 2D materials











- Need for reliable process tools
- Development in collaboration with end users
- Reliability and automation would be issues to look out for going from lab to fab
- 30+ years experience in providing a long term support to both research and production customers







# **Thank You!**



## **OIPT: Shaping The Future**

# Using innovation to turn smart science into world class products